

Title (en)
DEVICE AND METHOD FOR ENCASING AN ELECTRONIC COMPONENT

Title (de)
VORRICHTUNG UND VERFAHREN ZUR UMHÜLLUNG EINES ELEKTRONISCHEN BAUELEMENTS

Title (fr)
DISPOSITIF ET PROCEDE PERMETTANT D'ENVELOPPER UN COMPOSANT ELECTRONIQUE

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Application
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Abstract (en)
[origin: WO0239487A2] The invention relates to a device (1) and to a method for encasing an electronic component (10). According to the invention, the device (1) comprises a sleeve (100) and a casting compound (200), whereby said casting compound (200) is hardened. The casting compound (200) is one that hardens at an accelerated rate when exposed to water molecules, and the sleeve (100) provides the water molecules.

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